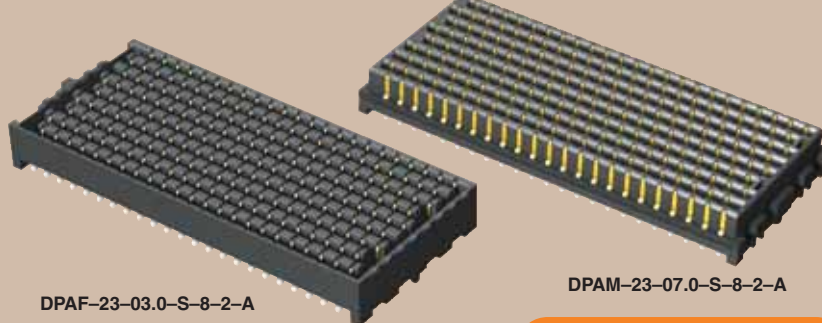


(2,16 mm) .085"



DPAM-23-03.0-S-8-2-A

DPAM-23-07.0-S-8-2-A

DPAM, DPAF SERIES

# HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:  
DPAF

DPAF Mates with:  
DPAM

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?DPAM](http://www.samtec.com?DPAM) or [www.samtec.com?DPAF](http://www.samtec.com?DPAF)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Plating:**

Au over 50µ" (1,27 µm) Ni

**Current Rating (2x3):**

2.9 A per pin

**Operating Temp Range:**

-55°C to +125°C

**Contact Resistance:**

10.4mΩ

**Working Voltage:**

300 VAC

**Mated Cycles:** 100 Cycles

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

**Protocols Supported**

Fibre Channel

Rapid I/O

PCI Express®

SATA

InfiniBand™

XAUI

MGT (Rocket I/O)

Download app notes at:

[www.samtec.com/appnote](http://www.samtec.com/appnote)

Contact SIG @ samtec.com

for questions on protocols

**ALSO AVAILABLE**  
(MOQ Required)

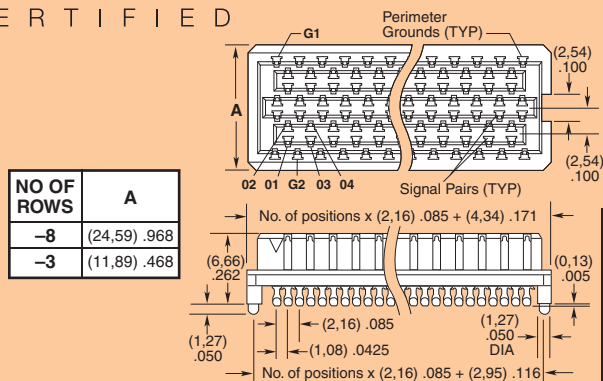
- Tin-Lead Solder Charge
- Other platings
- Contact Samtec.

**Note:** Patented

**Note:** Some sizes, styles and options are non-standard, non-returnable.

| DPAM | PAIRS PER ROW             | 07.0 | PLATING OPTION                                                       | NO. OF ROWS                                                | SOLDER TYPE                                                                 | A | OPTION                                                                                                                                  |
|------|---------------------------|------|----------------------------------------------------------------------|------------------------------------------------------------|-----------------------------------------------------------------------------|---|-----------------------------------------------------------------------------------------------------------------------------------------|
|      | -04, -06<br>-08, -15, -23 |      | -S<br>=30µ" (0,76 µm)<br>Gold on contact area,<br>Tin on solder tail | -8<br>=Eight<br>Pair Rows<br><br>-3<br>=Three<br>Pair Rows | -2<br>= Lead-Free<br>Tin Alloy<br>96.5% Sn/<br>3% Ag/.5% Cu<br>Solder Crimp |   | -K<br>=(20,00 mm) 0.80"<br>DIA Polyimide<br>film Pick &<br>Place Pad<br><br>-TR<br>=Tape & Reel<br><br>-GP<br>=Guide Post<br>(-23 only) |

**Final Inch**  
CERTIFIED



| NO OF ROWS | A            |
|------------|--------------|
| -8         | (24,59) .968 |
| -3         | (11,89) .468 |

| DPAM/DPAF 10 mm Stack Height | Rated @ 3dB Insertion Loss* |
|------------------------------|-----------------------------|
| Single-Ended Signaling       | 8 GHz / 16 Gbps             |
| Differential Pair Signaling  | 7 GHz / 14 Gbps             |

\*Performance data includes effects of a non-optimized PCB. Complete test data available at [www.samtec.com?DPAM](http://www.samtec.com?DPAM), [www.samtec.com?DPAF](http://www.samtec.com?DPAF) or contact sig@samtec.com

| DPAF | PAIRS PER ROW              | 03.0 | PLATING OPTION                                                       | NO. OF ROWS                                                | SOLDER TYPE                                                              | A | OPTION                                                                                                |
|------|----------------------------|------|----------------------------------------------------------------------|------------------------------------------------------------|--------------------------------------------------------------------------|---|-------------------------------------------------------------------------------------------------------|
|      | -04, -06, -08,<br>-15, -23 |      | -S<br>=30µ" (0,76 µm)<br>Gold on contact area,<br>Tin on solder tail | -8<br>=Eight<br>Pair Rows<br><br>-3<br>=Three<br>Pair Rows | -2<br>= Lead-Free Tin Alloy<br>96.5% Sn/ 3%Ag/<br>.5% Cu<br>Solder Crimp |   | -K<br>=(20,00 mm)<br>0.80" DIA<br>Polyimide<br>film<br>Pick &<br>Place Pad<br><br>-TR<br>=Tape & Reel |

| NO OF ROWS | A            |
|------------|--------------|
| -8         | (23,32) .918 |
| -3         | (10,62) .418 |

| SIZE     | USABLE PAIRS PER ARRAY* |
|----------|-------------------------|
| -04 x -3 | 6 Pairs                 |
| -06 x -3 | 12 Pairs                |
| -04 x -8 | 16 Pairs                |
| -06 x -8 | 32 Pairs                |
| -08 x -8 | 48 Pairs                |
| -15 x -8 | 104 Pairs               |
| -23 x -8 | 168 Pairs               |
| -08 x -3 | 18 Pairs                |
| -15 x -3 | 39 Pairs                |
| -23 x -3 | 63 Pairs                |

\*Assumes first and last pair in each row are grounded

| DPAM LEAD STYLE | DPAF MATED HEIGHT* |
|-----------------|--------------------|
| -07.0           | 10 mm              |

\*Processing conditions will affect mated height.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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